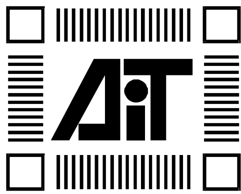

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PRIMA-BOND

EG7635

Ambient Curable
Thermally Conductive
2-Component Epoxy Paste
High Bond Strength

IDEAL FOR:

- **Heat-Sink Attach**
- **Substrate Attach**
- **Component Attach**

DESCRIPTION:

EG7635 is a alumina filled, electrically insulating and thermally conductive rigid epoxy paste adhesive. While bonding at ambient temperature can be achieved overnight, elevated temperatures will accelerate curing, exponentially. EG7635 high thermal conductivity and high strength makes it excellent for bonding substrates, components and heat sinks where thermal management is critical. It has more than 15 years of proven records of providing bonding to difficult substrates.

EG7635 exibits reduced bond strength at 80-100ºC for easier rework.

TYPICAL PROPERTIES*

Property	Value
Electrical Resistivity (150 ºC/ 60 minutes)	>1X10 ^{14} ohm-cm
Dielectric Strength (Volts/mil)	> 750
Glass Transition Temp.(ºC)	60 ±10%
Current Carrying Capabilities	N/A
Lap-Shear Strength	>>1000 psi >>6.9 N/mm²
Device Push-off Strength	>>2500 psi >>17.2 N/mm²
Cured Density (gm/cc)	2.3 ±10%
Thermal Conductivity	12 Btu-in/hr-ft²-ºF ±10% 1.7 W/m-ºC ±10%
Linear Thermal Expansion Coeff. (ppm/ºC)	45
Maximum Continuous Operation Temp. (ºC)	<150
Avg. Viscosity(0.5 rpm, 25ºC) (Brookfield DV-1, spindle CP51)	285,000 cp ±20%

* Properties given are typical values and not intended for use in preparing specifications. The user is advised to evaluate the product in the manner the product is intended to be used in manufacturing and in the final product.

AVAILABILITY:

EG7635 is available in syringes for automatic needle dispense applications or in jars. Upon request, the material can be shipped premixed and frozen. .

APPLICATION PROCEDURES:

(1) Store Part A and Part B at ambient.

(2) Mix A and B 1:1 by weight.

(3) Cure according to one of the recommended schedules.

****CURE SCHEDULES:**

Temperature	Time
25ºC	24 hr
80ºC	120 min
100ºC	60 min
125ºC	30 min
150ºC	15 min

**If the material is premixed and frozen, thaw for 30 minutes and apply cure according to one of the recommended cure schedules.

***Shelf life is for unmixed components. If premixed:-40ºC for 6 months. Pot life is 4 hours at 25ºC, after mixing.** Mixed components gel, an additional 80ºC at 120 min. is suggested for complete cure.

SHELF LIFE:

Storage temperature	Shelf Life
25ºC	***1 yr from ship date

CAUTION: This product may cause skin irritation. Avoid skin contact. If contact does occur, wash immediately with soap and water. Please refer SDS for more details.

The information contained herein is believed to be reliable. All recommendations or suggestions are made without guarantee inasmuch as conditions and methods of commercial use are beyond our control. Properties given are typical values and not intended for use in preparing specifications. The user is advised to evaluate the product in the manner the product is to be used in manufacturing and in the final product. Under no circumstance shall AI Technology be liable for accidental, consequential or other damages arising from the use or handling of this product.

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